

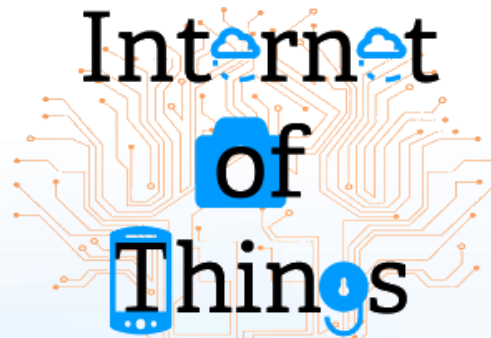
Internet  
of  
Things

The logo features the text "Internet of Things" in a black, serif font. The word "Internet" is at the top, "of" is in the middle, and "Things" is at the bottom. The letters are partially overlaid by a network of orange circuit lines. Several letters are replaced by blue icons: the 'e' in "Internet" is a cloud, the 'o' in "of" is a camera, the 'i' in "Things" is a smartphone, and the 'o' in "Things" is a lightbulb.

**Dejia/DJ Kong  
Advantest**

# IoT/loE/M2M/loTS

**Internet of Things (IoT)**  
**Internet of Everything (loE)**  
**Machine to Machine (M2M)**  
**Internet of Things & Services (loTS)**



**ADVANTEST®**

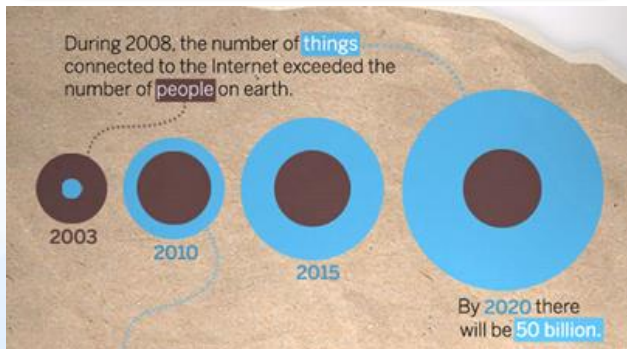
# IoT Concept

- A new wide range of applications enabled by the combination of :

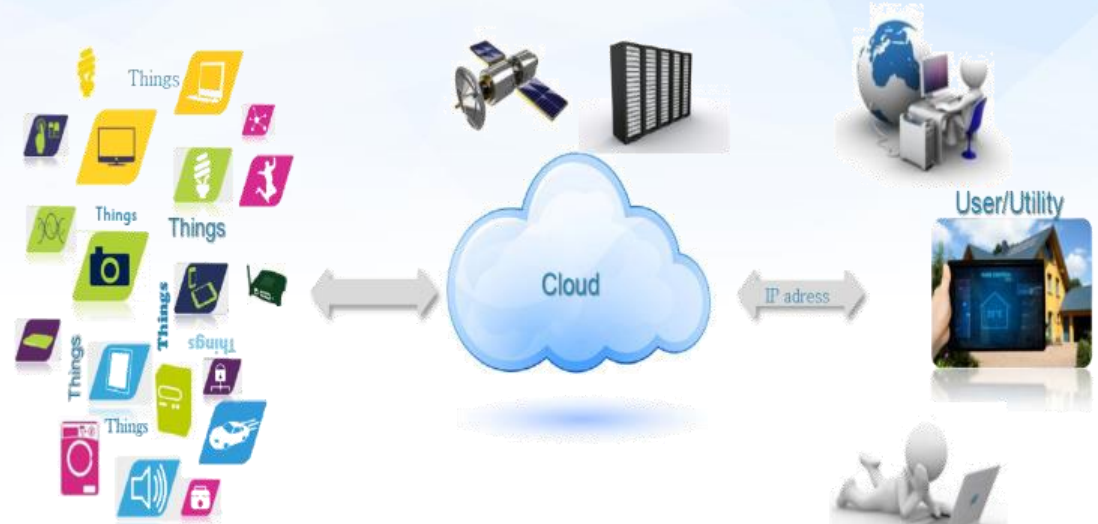
- Sensors / Actuators
- Computing ( + Software)
- Connectivity (Wireless, Wired)

- Largest Growth Market in the coming years

- 50B Installed units in 2020



Source: Cisco Blog



Source: STMicroelectronics

<b>Connectivity</b>  Wireless/Wired Narrow/Broad RFSubGHz - WiFi/BT BTLE - PLC - RFID - NFC	<b>Sensing</b>  Motion Environment MEMS - Accel - Gyro Pressure - Humidity Temp - Microphone	<b>Processing</b>  Ultra Low Power High Performance Cortex M0+/M3/M4
<b>Powering</b>  Efficiency Harvesting PV & TEG harvesting Battery Charger, Regulator	<b>Security</b>  Identification Authentication ISO 14443 ISO 15963 CRYPTO	<b>...others</b>  Certification Cost Effective ASIC, RTC, OPamp, Protection, Backup, etc...



Source: STMicroelectronics

**ADVANTEST®**

# Building Blocks → Sensors / Actuators

- Established and emerging technologies:

- Motion Mems:

- » Accelerometers, Gyroscopes, Compasses

- Environmental:

- » Barometric Pressure, Temperature, Humidity, UV, CO, CO2, Air Quality, Gas Flow sensing

- Health:

- » Blood Pressure, Glucose Monitor, Heart Rate, ECG Monitor

- Optical Sensors:

- » Proximity, Ambient Light, RGB Color Image Sensors

- Touch Sensors:

- » Multi-Touch, Touch less Hover, Pressure Touch

- RF Sensors:

- » GPS / A-GPS, Wi-Fi , BT Low Energy, NFC

- Other Sensors:

- » MEMS Microphones, Biometric Sensors, Fingerprint, Bio Sensors



Accelerometers



Fingerprint



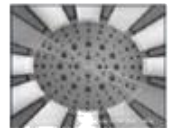
Optical MEMS



Others



RF MEMS



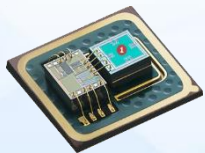
Gyroscopes



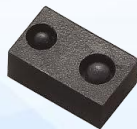
Microfluidics



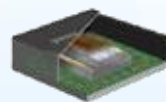
Magnetometers  
(Digital Compass)



Pressure Sensor



Proximity



Inertial Combos



Si Microphones

**ADVANTEST®**

# Building Blocks → Computing

- Many requirements depending on target application
  - Low Power is the Key
  - Medium Flash size 32KB-256KB
- ARM Microcontroller is mostly used but not only
  - STM → STM32F2 Cortex™ M0 , STM32LO Cortex™ M4
  - ADI → ADUCRF101 Cortex™ M3, ADUC702632 ® MCU
  - TI → 66K2Hx I multicore DSP+ Cortex™-A15
  - QUALCOMM → SnapDragon™



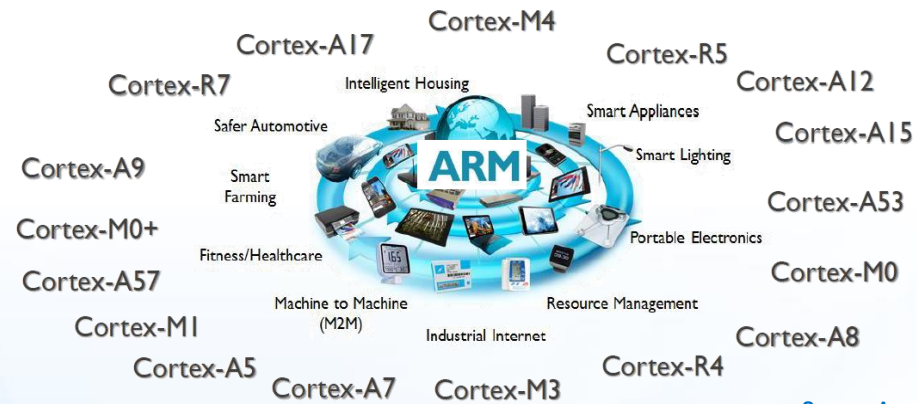
Source: Texas Instruments



**STM32LO:**  
MCU Cortex M0+



**STM32F2**  
Cortex M4 - High Performance MCU



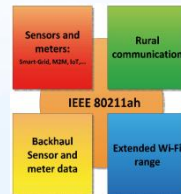
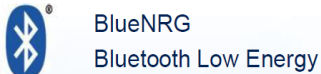
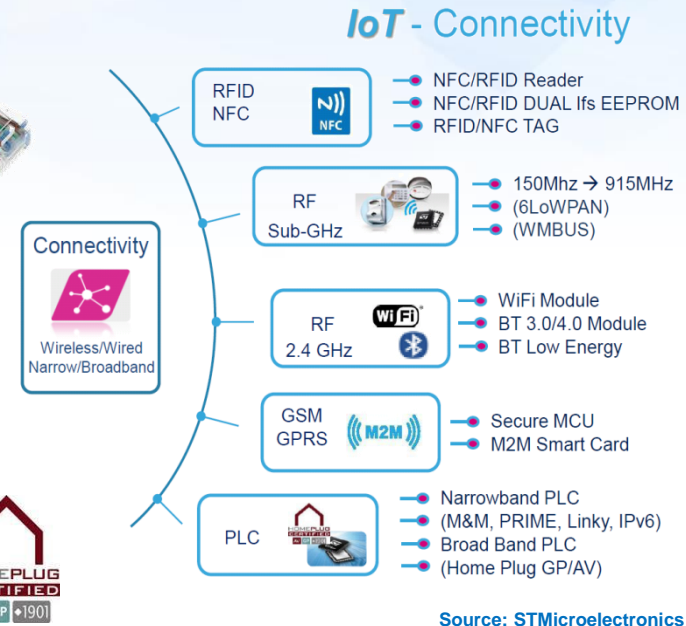
Source: Arm





# Building Blocks → Connectivity

- Many different solutions
  - Low Power is the Key (Low Data Rate)
  - Medium Range 90% of the Market < 100m
- Standard and proprietary Wireless protocols
  - 2.4 Gz : BluetoothNRG, WiFi
  - Sub Ghz : NFC, RFID, Z-Wave, Zigbee, Spirit-1
- Standard and proprietary Wired protocols
  - Ethernet, Mbus
  - LonWorks, KNX






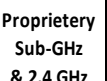










<ul style="list-style-type: none"> <li>• Low power mesh network</li> <li>• Smart metering &amp; lighting</li> <li>• Moving into home automation</li> </ul>	<ul style="list-style-type: none"> <li>• Low power &amp; long range</li> <li>• Proprietary &amp; open protocols</li> <li>• Metering, security systems</li> </ul>
<ul style="list-style-type: none"> <li>• Fast – 10Mbps++</li> <li>• Direct Internet connection</li> <li>• Home &amp; enterprise apps</li> </ul>	<ul style="list-style-type: none"> <li>• Lowest power</li> <li>• Connect to tablet/phone</li> <li>• Moving to industrial, automotive</li> </ul>
<ul style="list-style-type: none"> <li>• Data over power lines (OFDM)</li> <li>• Developed for smart grid</li> <li>• Lighting, solar, appliances</li> </ul>	<ul style="list-style-type: none"> <li>• Fast, low latency Ethernet</li> <li>• Real-time industrial control</li> <li>• Information technology</li> </ul>

Source: Texas Instruments

# RF Connectivity Pro & cons

- Power/Range/Cost are the 3 axis
- Security adding additional constraints
- Application success will drive Standards

RF STANDARD														
Network	PAN	PAN	PAN	PAN	PAN	LAN	LAN	LAN	LAN	LAN	LAN	LAN	MAN	WAN
Topology	P2P	P2P	Star	Star	P2P, Star, Tree Mesh	Star, Mesh	Star	Mesh, Star, Tree	Mesh	Mesh, Star, Tree	Mesh, Star	Mesh, Star	Mesh	Mesh
Power	Very Low	Very Low	Low	Very Low	Very Low	Very Low to Low	Low-High	Very Low	Very Low	Very Low	Very Low	Very Low	High	High
Speed	400 Kbs	400 Kbs	700 kbs	1 Mbs	1 Mbs	250 kbs	<100 Mbs	250 kbs	40 Kbs	1.2 Kbps	250 kbs	250 Kbs	<100 Mbs	<7.2 Mbs
Range	<10 cm	<3 m	<30 m	5-10 m	1-30 m	10-70 m	4-20 m	10-300 m	30 m	800 m	200	800 m SubGHz	50 km	Cellular network
Applications	Pay, get access, share, initiate service, easy setup	Item tracking	Network for data exchange, headset	Health and fitness	Sports and fitness	Point to point connectivity	Internet, multimedia	Sensor networks, building and industrial automation	Residential lighting and automation	Building automation	Industrial sensing networks	Senor networks, building and industrial automation	Metro area broadband Internet connectivity	Cellular phones and telemetry
Cost Adder	Low	Low	Low	Low	Low	Medium	Medium	Medium	Low	Medium	Medium	Medium	High	High

# Different Integration opportunities

- Module (System on board)

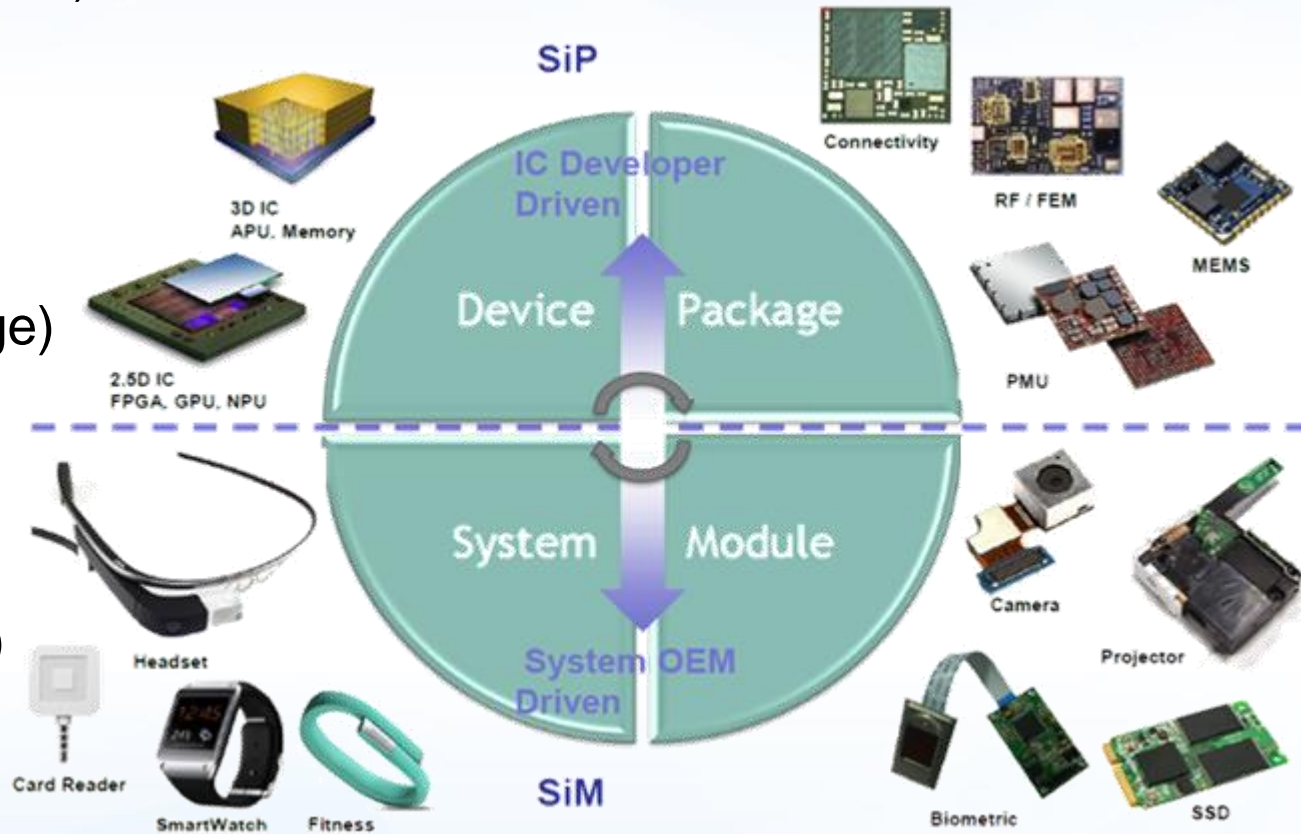
- Short time to market
- Low risks
- High costs

- SIP (System in Package)

- Enabling HVM
- Medium risks
- Medium costs

- SOC (System on Chip)

- Enabling Profit
- Highest risks
- Lowest costs

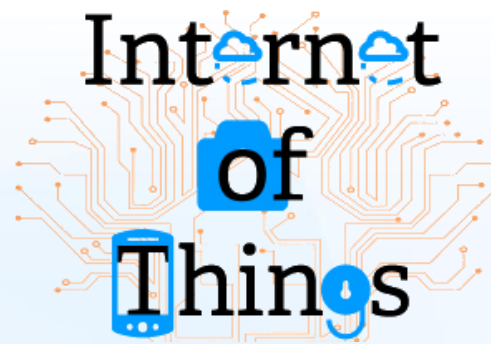


Source: IC ASE Group

**ADVANTEST®**



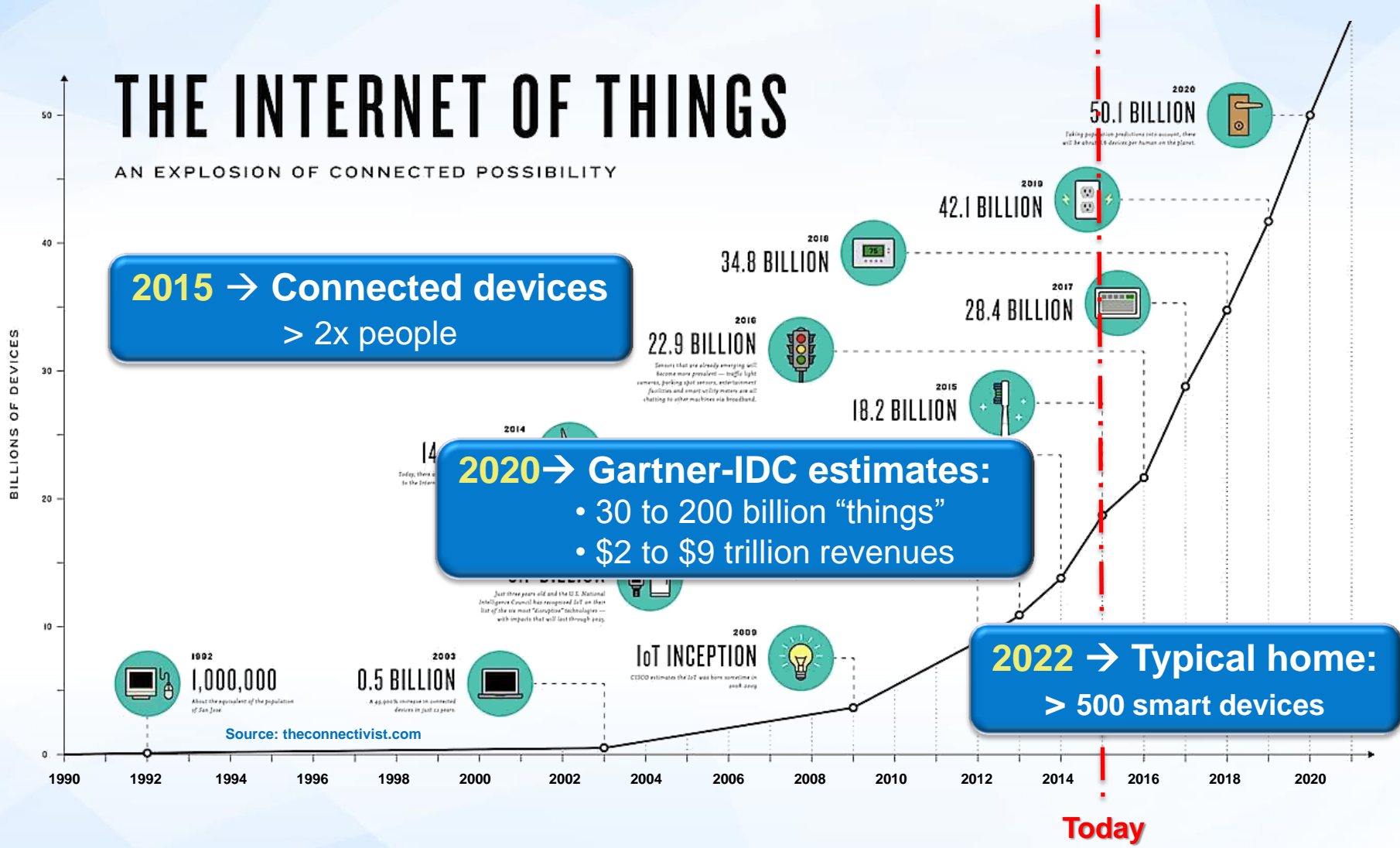
# **IoT Expected Growth**



# Roadmap for 50 Billion connected devices

## THE INTERNET OF THINGS

AN EXPLOSION OF CONNECTED POSSIBILITY



**2015** → Connected devices  
 > 2x people

**2020** → Gartner-IDC estimates:

- 30 to 200 billion “things”
- \$2 to \$9 trillion revenues

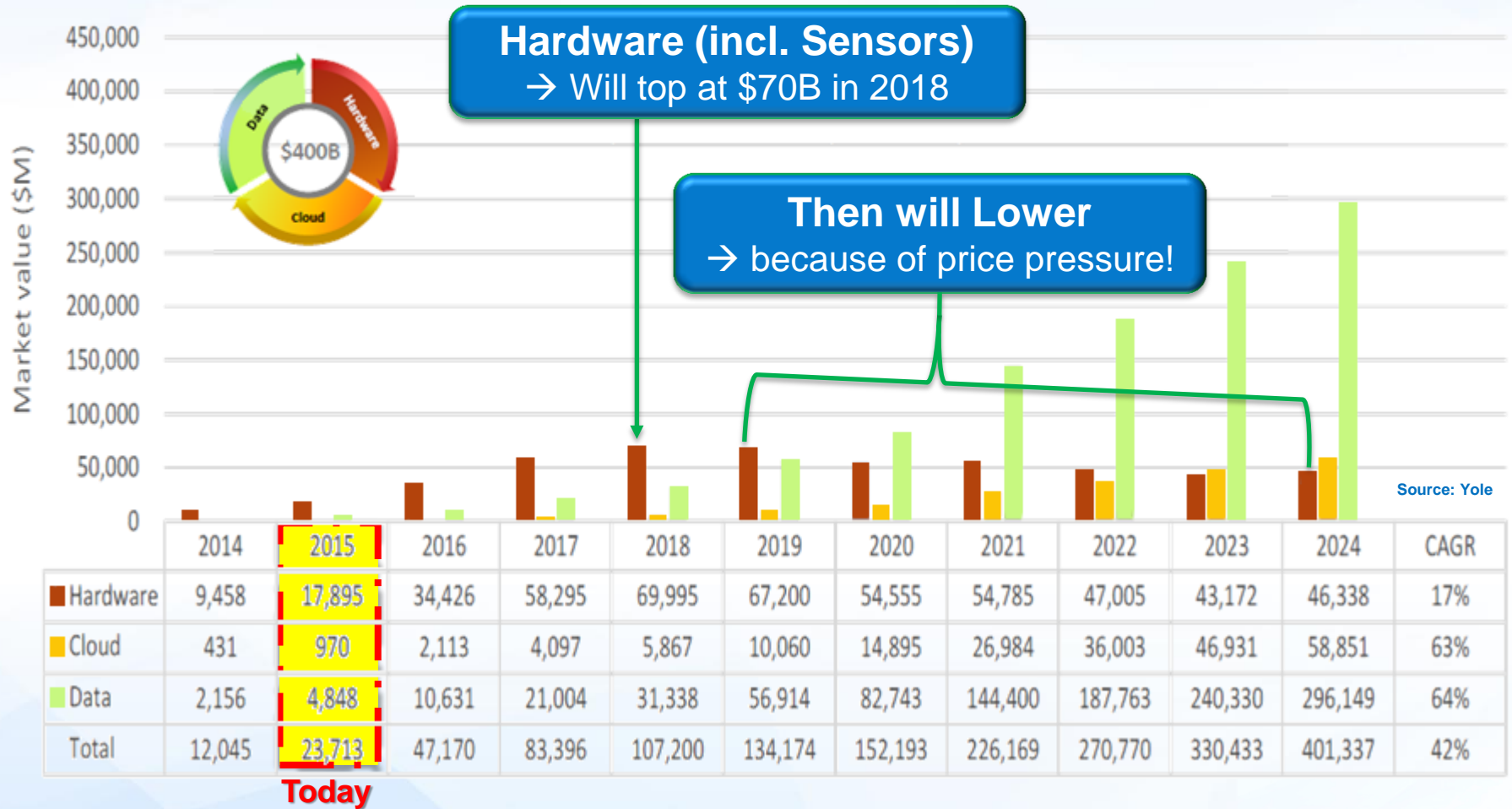
**2022** → Typical home:  
 > 500 smart devices

Today



# IoT Expected Growth

Market Value Repartition in IoT Structure (\$M)



# An explosion of Market Players

## Smartphone/Tablet Market Wave

- Few application Types
- 5 billions Devices
- Few Players to covers 80% of Revenues



## IoT Market Wave

- A wide variety of applications
- 50 billions Devices
- Top Players will address less than 40%

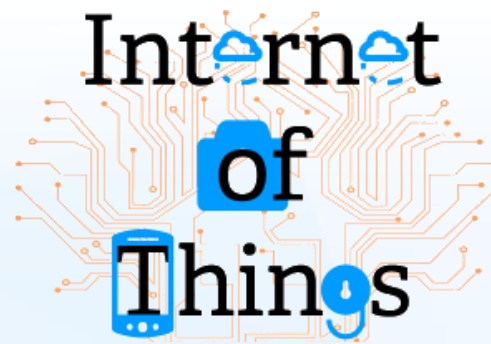
**10 x Volumes**  
**100 x Applications**  
**1000 x Players**



- 100 x applications to drive 10x device volumes:
  - Few High Volume Runners
  - Many Medium Volume Runners
- Testing Flexibility to be a key requirement to support applications variety
  - Same Test Cell to support many type of devices
- Hundreds of Tier-2 players forced to implement Fabless model
  - Cannot invest in Test equipment to Match ASP
  - A step of flexibility increase required at OSAT

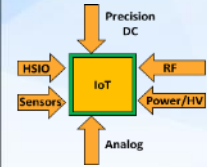
**ADVANTEST®**

# **IoT Test Challenges**





# IoT Test Challenges



**Integration** creates new device class

- Compute/Security, Communication, Smart Power, Sensors & Actuators



**Low power** devices

- Smaller voltage swings
- Low leakage



**Cost** pressure

- High volume, falling ASP



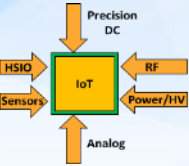
**Unpredictability** of emerging market

- Low volume/High mix (High runners?)
- In-house vs Outsource

*Technical & economic trends are breaking installed tester base*

**ADVANTEST**

# IoT Test System Requirements



**Integration** creates new device class

- Compute/Security, Communication, Smart Power, Sensors & Actuators

→ ATE system covering all domains (Dig/HS/DC/MX/RF/Memory)

→ Universal Pins

**Low power** devices

- Smaller voltage swings
- Low leakage

→ DC accuracy

**Cost** pressure

- High volume, falling ASP

→ High throughput (test-time & MSE)

→ COT optimized test solutions

**Unpredictability** of emerging market

- Low volume/High mix (High runners?)
- In-house vs Outsource

→ Fast Time to Quality

→ Expandability of ATE system

→ Availability at OSATs

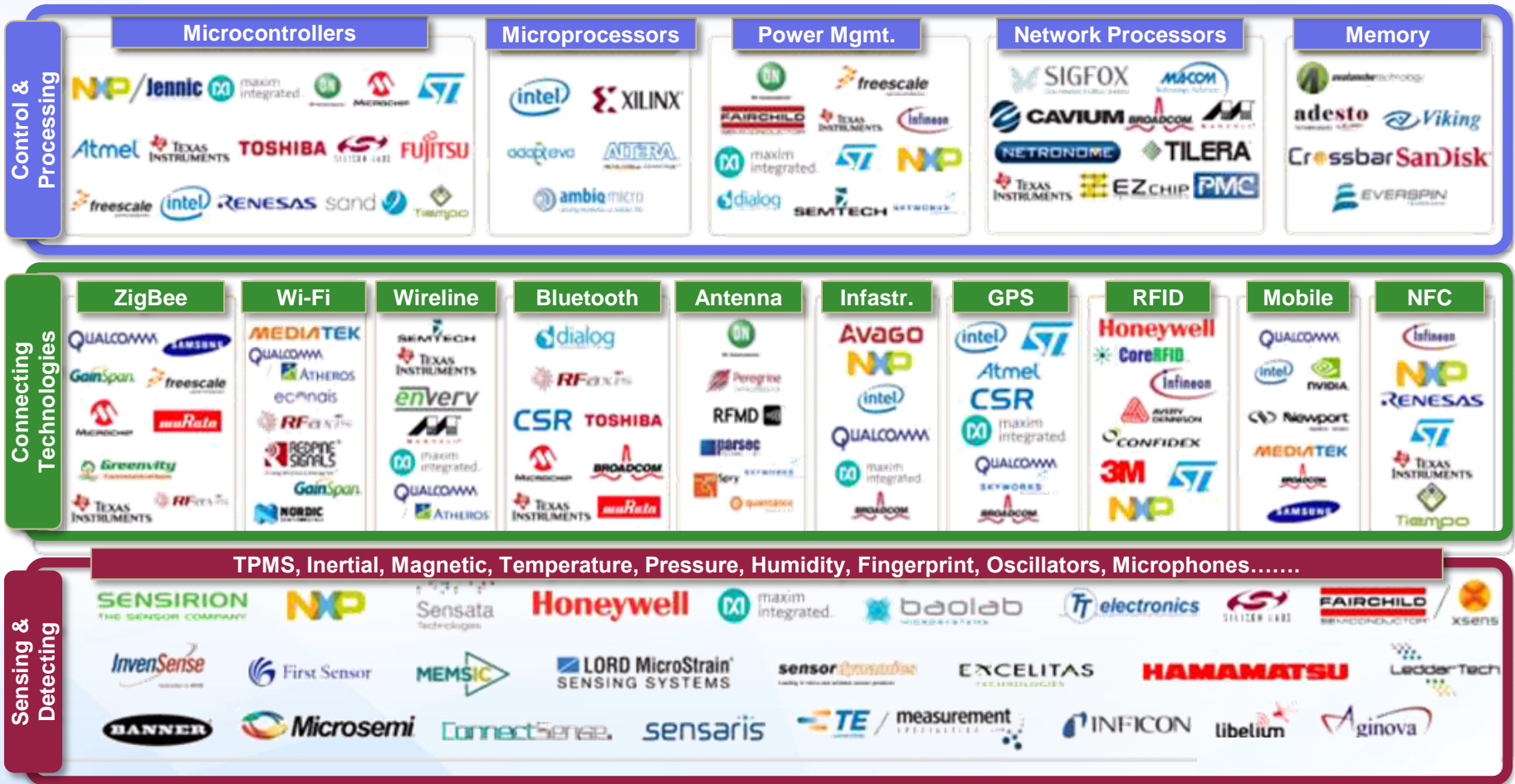
*Technical & economic trends are breaking installed tester base*

**ADVANTEST**

# IoT Market Map

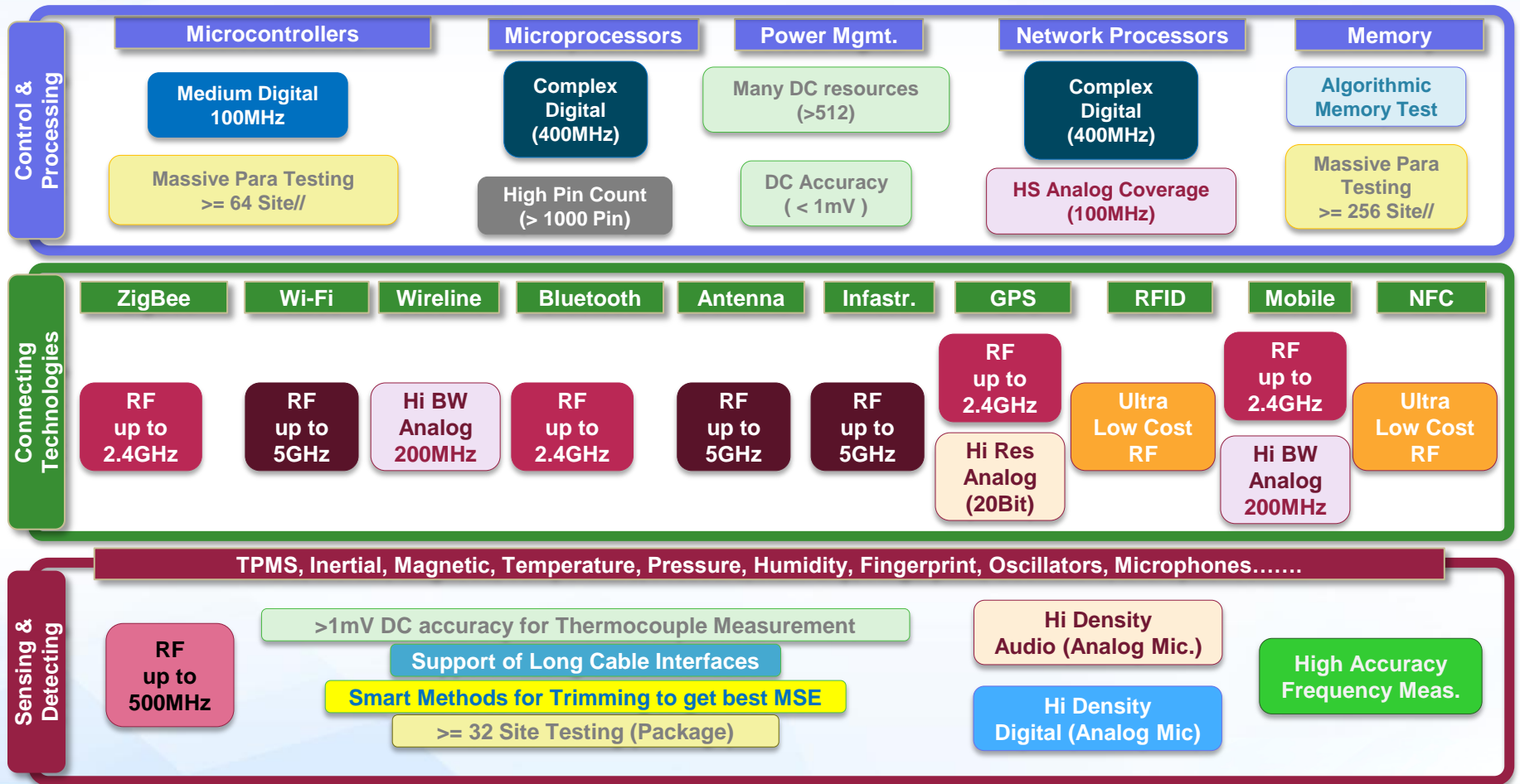
- Processing & Control still will dominate IOT Scenario
- Connecting Technologies to play significant role
- Sensor & Actuators will follow

Source: Mooreland Partners

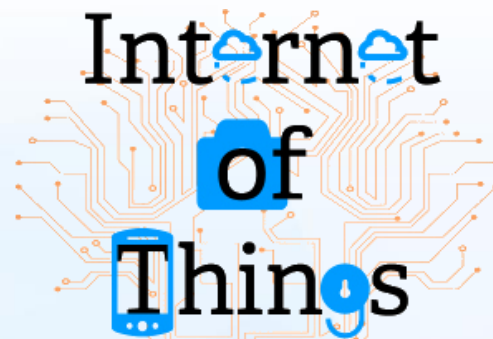


# IoT Market needs

- Best Flexibility
- High Parallelism and High Multi-Site Efficiency (MSE)
- High Accuracy



# **IOT Tester Architecture Requirements**





# Universal Pin Concept for IoT

## Digital

- Excellent signal fidelity (from kHz to 1.6Gbps)
- Voltage range - 2.0 .. 6.5 V
- SCAN: narrow, wide and SerDes
- All protocols (I2C, SPI, DSI3, SPI5, ...)
- OTP / eFlash programming / testing
- Driving large capacitance loads

## RF

- RF Spectrum Analyzer up to 800MHz

## DC / VI

- Sequencer/pattern controlled
- Precise voltage/current measurements (1mV, 10nA)
- Device trimming/calibration in parallel

## DPS

- PPMU as low current power supply
- Up to 40mA (60mA /16 pins per module),slew control
- Idd (quiescent (10nA), operating, standby)

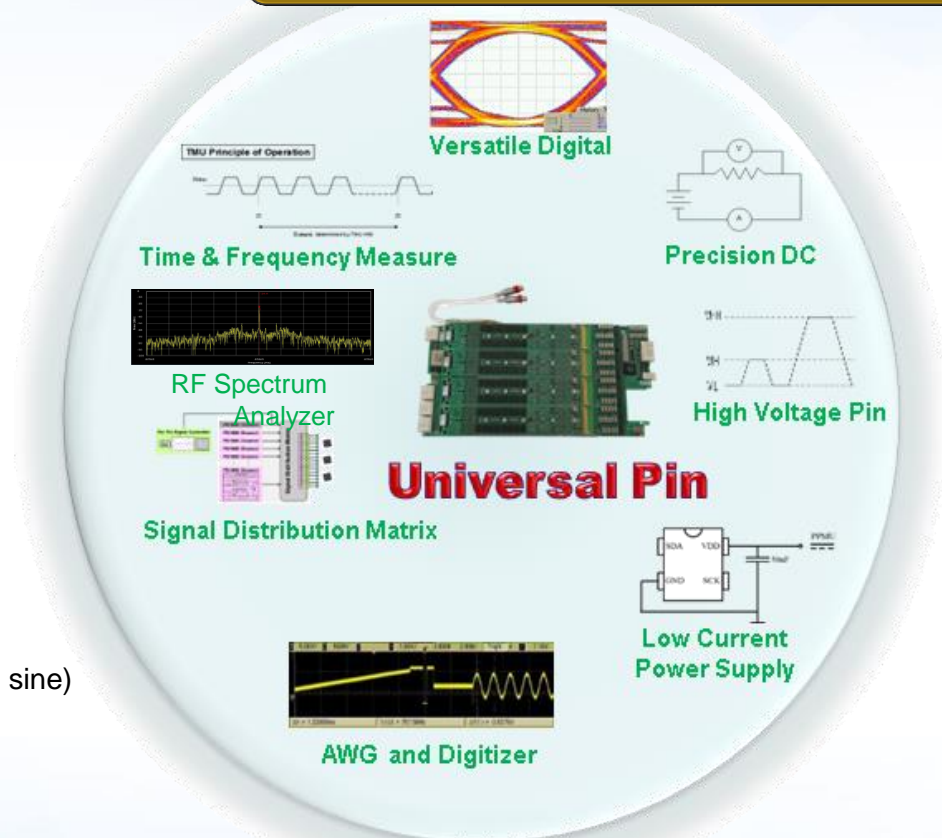
## Analog

- AWG per pin: for static & dynamic test (>86dB @ 20KHz sine)
- Digitizer per pin: 54 Ksps static, 250 Ksps dynamic

## Frequency & Time Measurement Unit

- Fast and accurate time measurements (frequency, jitter) (50Msps, 35ps accuracy)

128 ... 1024 "Universal Pins"  
in V93000 A-Class Test Head!



Tester resources for all device functions behind each pin

**ADVANTEST**

# Higher Performance Tester Requirements for IoT

## Higher performance Digital IO

- Higher speed Serial and/or Parallel interfaces (eg SERDES, Memory Interfaces, ...)

## Higher performance DPS / DC / VI

- Higher Power voltage/current measurements

## Higher performance Analog

- Higher performance AWG and Digitizer for static & dynamic test

## Higher performance RF

- RF Source and Measure

Optional

**DPS128** 128ch  
15V

**PS9G** 64ch  
>8G

**VI32** 32ch  
25V

**Port  
Scale RF** 6Ghz

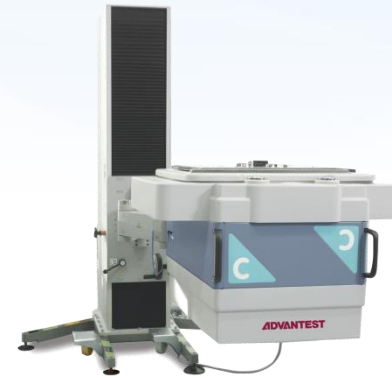
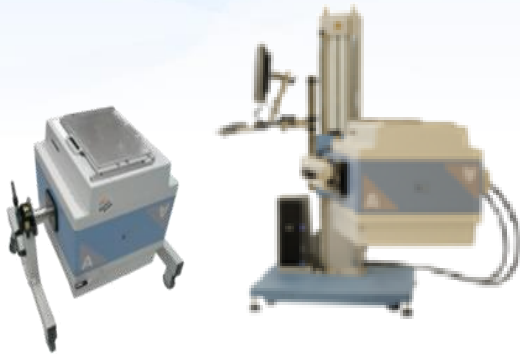
**AV8+** 4 AWG, 4 DIG  
Hi-Res/Hi-Freq.

**PVI8** 8ch  
Power

Higher Performance Tester resources available as options if needed

**ADVANTEST**

# Scalable Test Platform for IOT



- Smaller, low pin-count configurations
  - Lowest capex
  - Smaller devices
  - Engineering, “Lower” Volumes

- Larger, high pin-count configurations
  - Larger devices
  - Higher levels of multi-site
  - “Higher” Volumes

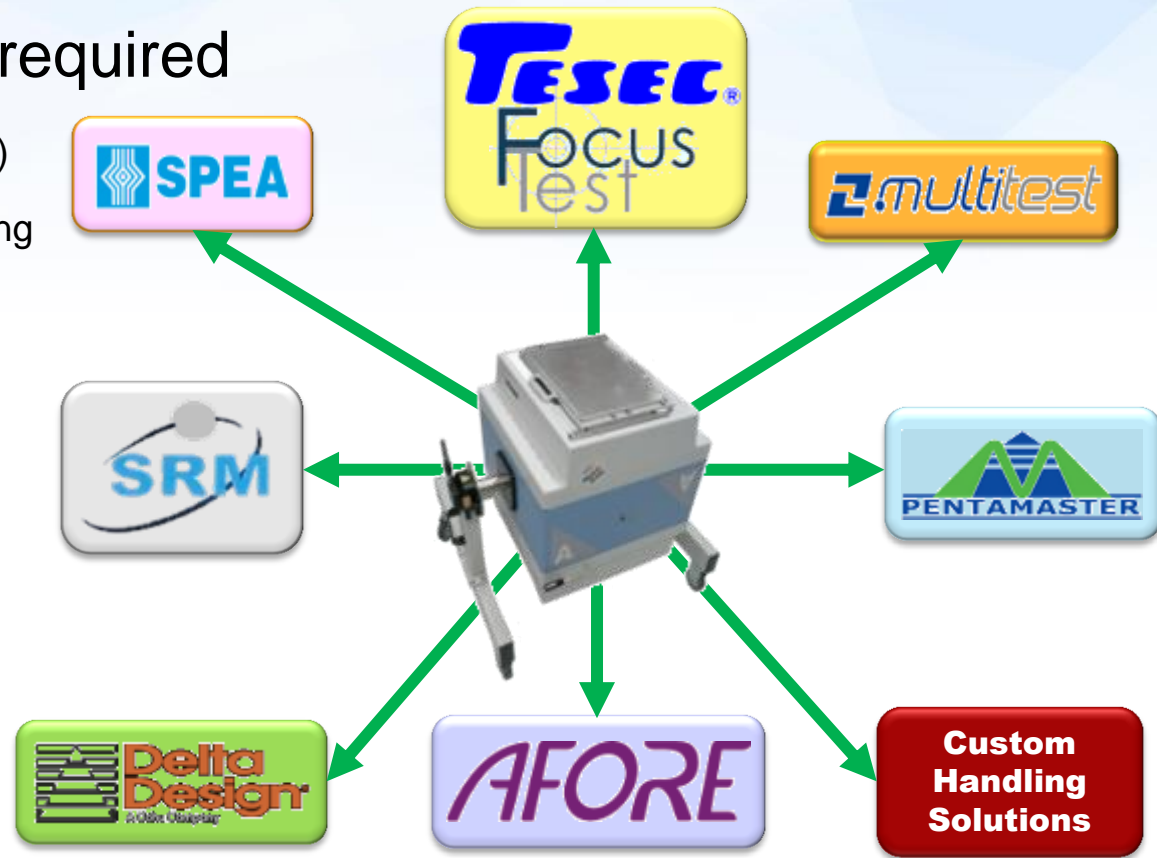
*Same Performance, Same SW, Same DUT board, Same Wafer Prober/Handler I/F*

**ADVANTEST®**

# IoT Sensors Handling & Stimulus

## • Test Cell Solution is required

- Tester (~25% of test Cell cost)
- Handler for HVM & Engineering
- Sensor Stimulus
  - Inertial
  - Temp/Hum
  - Pressure
  - Magnetic



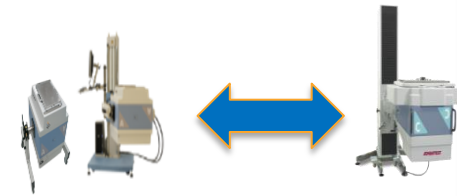
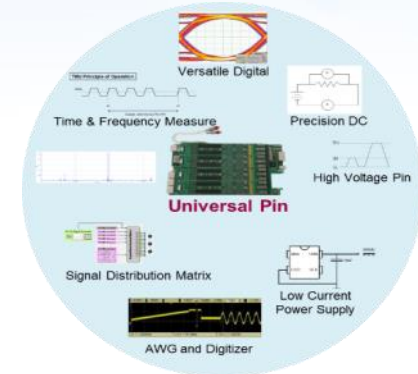
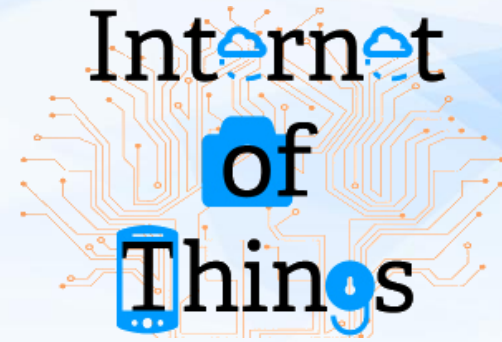
## • Partnership with Sensors Handler Manufacturers

- Propose 'turnkey' solutions for new players
- Unique interface with customer for problems solving

**ADVANTEST®**

# IoT Test Platform

- **Integrates** Digital, DPS, Analog, Mixed Signal, RF and Memory Test in one scalable platform
- **Universal Pins** for maximum flexibility & slim configuration
- **Scalable** from small, low pin count configurations (for lowest capex), to larger, high pin count configurations (for highest levels of multi-site) with the same performance and HW/SW compatibility
- **Broad availability** in market and in OSATs



**ADVANTEST®**



**Thanks you for your attention!**



**ADVANTEST®**